

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Previously Presented) A substrate with a microstructure formed thereon, the substrate comprising:

a lower substrate supporting an upper substrate ;

a buffer layer formed on an upper surface of the lower substrate to have a plurality of shapes with air gaps defined between each of said shapes and spaced apart from each other at regular intervals; and

an adhesive layer formed between the upper substrate and the buffer layer so that the upper substrate is removably adhered to the lower substrate by the adhesive layer and the buffer layer;

wherein, the upper substrate has a substantially higher flexibility than that of the lower substrate, and on which a device is formed.

2. (Previously Presented) The substrate as claimed in claim 1, wherein the lower substrate is made of at least one of Si, SiO₂, Al₂O₃, copper, copper alloy, aluminum, aluminum alloy, and glass.

3. (Original) The substrate as claimed in claim 1, wherein the buffer layer is made of at least one of SiO₂, Al₂O₃, AlON, SiON, Si₃N₄, AlN, SOG (spin-on-glass), photosensitive material, Cu, Cu alloy, Al, and Al alloy.

4. **(Currently Amended)** The substrate as claimed in claim 1, wherein the buffer layer is patterned and etched to form a plurality of shapes arranged in many rows or to form a plurality of shapes arranged in hexahedron or cylindrical islands, with stress relaxing air gaps being spaced apart from each other at regular intervals.

5. (Original) The substrate as claimed in claim 1, wherein the adhesive layer is made of any one of a double sided tape, a liquid adhesive, and organic film, to withstand a hot process of more than 100.degree. C.

6. (Original) The substrate as claimed in claim 1, wherein the upper substrate is made of any one of plastic, stainless steel, copper, copper alloy, aluminum, aluminum alloy, silicon, and glass.

7-14. (Canceled).